# LNJ115W8ARA

# Surface Mounting Chip LED

## TSS-2 Type

## ■ Absolute Maximum Ratings $T_a = 25$ °C

#### • Yellow Green

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	60	mW	
Forward current	$I_{\mathrm{F}}$	20	mA	
Pulse forward current *	$I_{FP}$	60	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

#### Orange

Parameter	Symbol	Rating	Unit	
Power dissipation	P <sub>D</sub>	60	mW	
Forward current	$I_{\rm F}$	20	mA	
Pulse forward current *	$I_{FP}$	60	mA	
Reverse voltage	$V_R$	3	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

### ■ Electro-Optical Characteristics $T_a = 25$ °C

#### • Yellow Green

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	Io	$I_F = 10 \text{ mA}$	1.8	5.0		mcd
Reverse current	$I_R$	$V_R = 4 V$			10	μΑ
Forward voltage	$V_{\rm F}$	$I_F = 10 \text{ mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 10 \text{ mA}$		565		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		30		nm

### ■ Lighting Color

- Yellow Green
- Orange

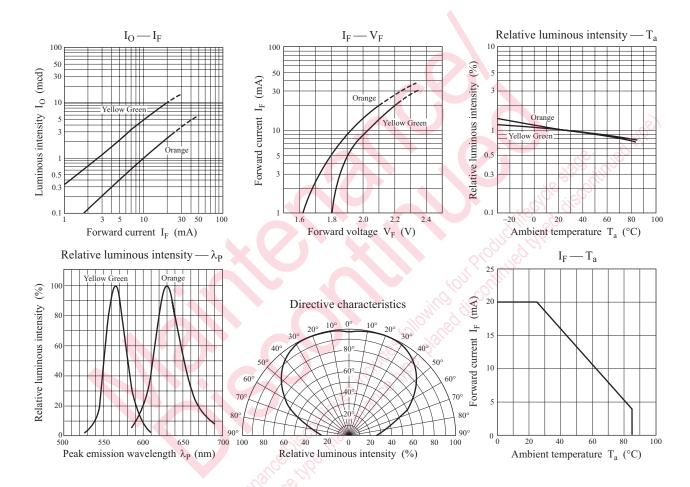
LNJ115W8ARA

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## ■ Electro-Optical Characteristics (Continued) $T_a = 25$ °C

#### • Orange

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I <sub>O</sub>	$I_F = 10 \text{ mA}$	0.4	1.0		med
Reverse current	$I_R$	$V_R = 3 V$			10	μΑ
Forward voltage	$V_{\mathrm{F}}$	$I_F = 10 \text{ mA}$		1.93	2.6	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		630		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		40		nm

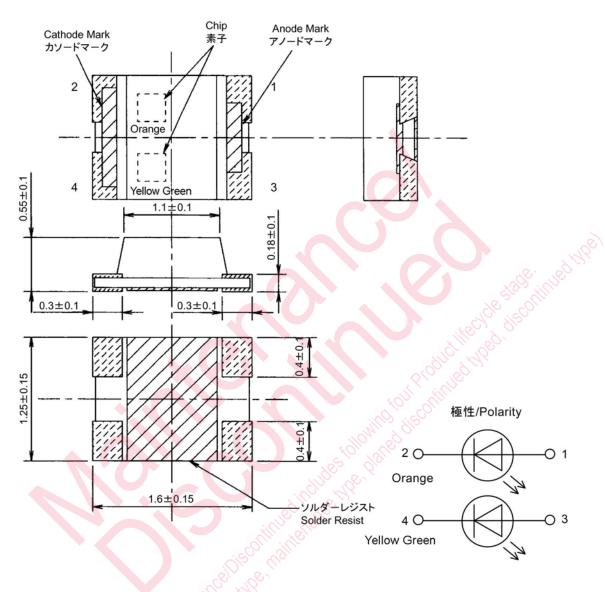


2 SHD00585CEK

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■ Package (Unit: mm)

# KLTFTN4K1540



- Pin name
  - 1, 3: Anode
  - 2, 4: Cathode

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